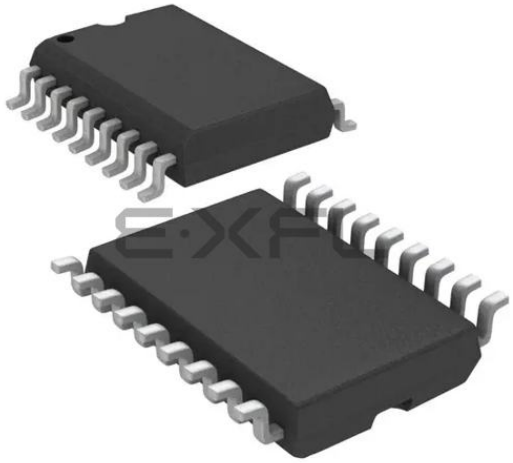

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c54ct-20-so

4.0 OSCILLATOR CONFIGURATIONS

4.1 Oscillator Types

PIC16C5Xs can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1:FOSC0) to select one of these four modes:

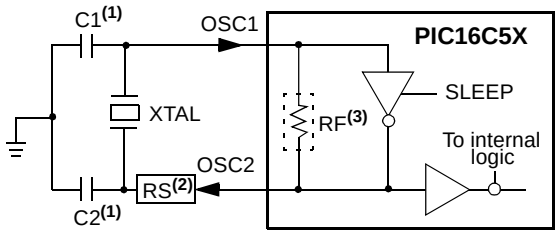
1. LP: Low Power Crystal
2. XT: Crystal/Resonator
3. HS: High Speed Crystal/Resonator
4. RC: Resistor/Capacitor

Note:	Not all oscillator selections available for all parts. See Section 9.1.

4.2 Crystal Oscillator/Ceramic Resonators

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 4-1). The PIC16C5X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source drive the OSC1/CLKIN pin (Figure 4-2).

FIGURE 4-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Capacitor Selection tables for recommended values of C1 and C2.
2: A series resistor (RS) may be required for AT strip cut crystals.
3: RF varies with the Oscillator mode chosen (approx. value = 10 MΩ).

FIGURE 4-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

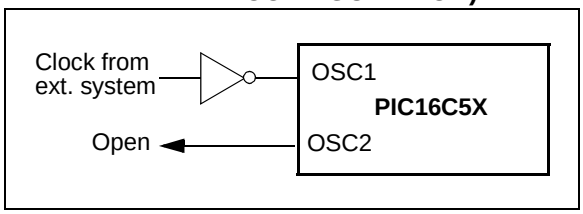


TABLE 4-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS - PIC16C5X, PIC16CR5X

Osc Type	Resonator Freq	Cap. Range C1	Cap. Range C2
XT	455 kHz	68-100 pF	68-100 pF
	2.0 MHz	15-33 pF	15-33 pF
	4.0 MHz	10-22 pF	10-22 pF
HS	8.0 MHz	10-22 pF	10-22 pF
	16.0 MHz	10 pF	10 pF

These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 4-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR - PIC16C5X, PIC16CR5X

Osc Type	Crystal Freq	Cap.Range C1	Cap. Range C2
LP	32 kHz(1)	15 pF	15 pF
XT	100 kHz	15-30 pF	200-300 pF
	200 kHz	15-30 pF	100-200 pF
	455 kHz	15-30 pF	15-100 pF
	1 MHz	15-30 pF	15-30 pF
	2 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15 pF	15 pF
	20 MHz	15 pF	15 pF

Note 1: For V_{DD} > 4.5V, C1 = C2 ≈ 30 pF is recommended.

These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

Note:	If you change from this device to another device, please verify oscillator characteristics in your application.

6.0 MEMORY ORGANIZATION

PIC16C5X memory is organized into program memory and data memory. For devices with more than 512 bytes of program memory, a paging scheme is used. Program memory pages are accessed using one or two STATUS Register bits. For devices with a data memory register file of more than 32 registers, a banking scheme is used. Data memory banks are accessed using the File Selection Register (FSR).

6.1 Program Memory Organization

The PIC16C54, PIC16CR54 and PIC16C55 have a 9-bit Program Counter (PC) capable of addressing a 512 x 12 program memory space (Figure 6-1). The PIC16C56 and PIC16CR56 have a 10-bit Program Counter (PC) capable of addressing a 1K x 12 program memory space (Figure 6-2). The PIC16CR57, PIC16C58 and PIC16CR58 have an 11-bit Program Counter capable of addressing a 2K x 12 program memory space (Figure 6-3). Accessing a location above the physically implemented address will cause a wraparound.

A NOP at the RESET vector location will cause a restart at location 000h. The RESET vector for the PIC16C54, PIC16CR54 and PIC16C55 is at 1FFh. The RESET vector for the PIC16C56 and PIC16CR56 is at 3FFh. The RESET vector for the PIC16C57, PIC16CR57, PIC16C58, and PIC16CR58 is at 7FFh. See Section 6.5 for additional information using CALL and GOTO instructions.

FIGURE 6-1: PIC16C54/CR54/C55 PROGRAM MEMORY MAP AND STACK

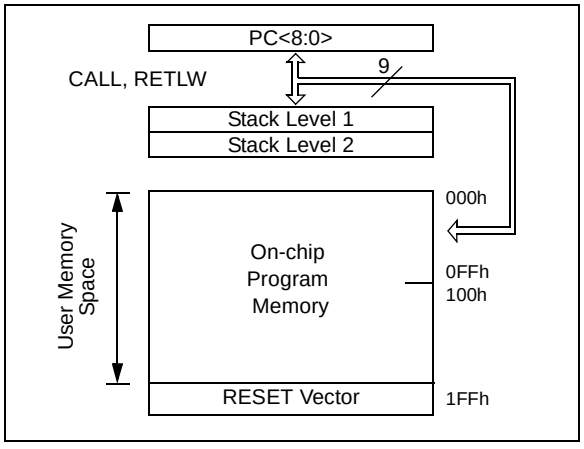


FIGURE 6-2: PIC16C56/CR56 PROGRAM MEMORY MAP AND STACK

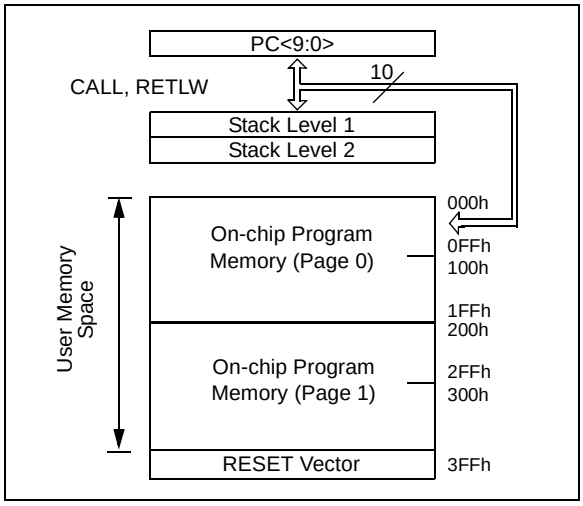
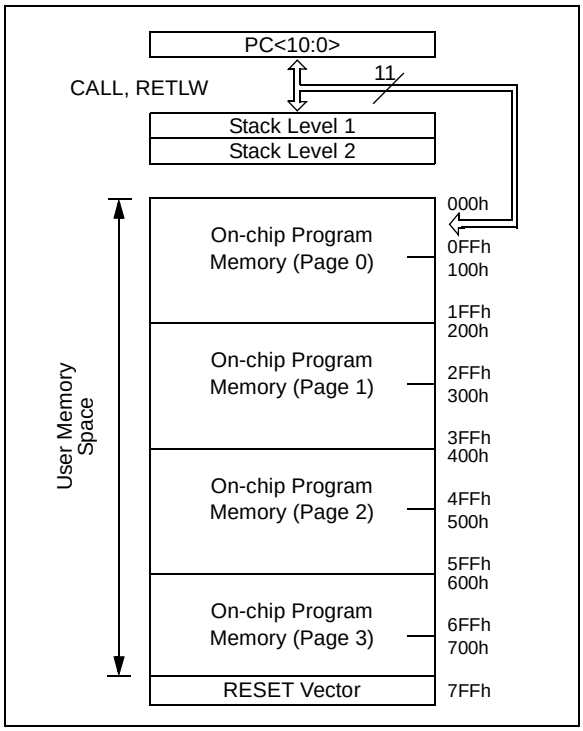


FIGURE 6-3: PIC16C57/CR57/C58/ CR58 PROGRAM MEMORY MAP AND STACK



6.7 Indirect Data Addressing; INDF and FSR Registers

The INDF Register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR Register (FSR is a *pointer*). This is indirect addressing.

EXAMPLE 6-1: INDIRECT ADDRESSING

- Register file 08 contains the value 10h
- Register file 09 contains the value 0Ah
- Load the value 08 into the FSR Register
- A read of the INDF Register will return the value of 10h
- Increment the value of the FSR Register by one (FSR = 09h)
- A read of the INDF register now will return the value of 0Ah.

Reading INDF itself indirectly (FSR = 0) will produce 00h. Writing to the INDF Register indirectly results in a no-operation (although STATUS bits may be affected).

A simple program to clear RAM locations 10h-1Fh using indirect addressing is shown in Example 6-2.

EXAMPLE 6-2: HOW TO CLEAR RAM USING INDIRECT ADDRESSING

```
            MOVLW   H'10'   ;initialize pointer
            MOVWF   FSR     ; to RAM
NEXT        CLRF    INDF    ;clear INDF Register
            INCF    FSR,F   ;inc pointer
            BTFSC   FSR,4   ;all done?
            GOTO    NEXT    ;NO, clear next
CONTINUE
            :               ;YES, continue
```

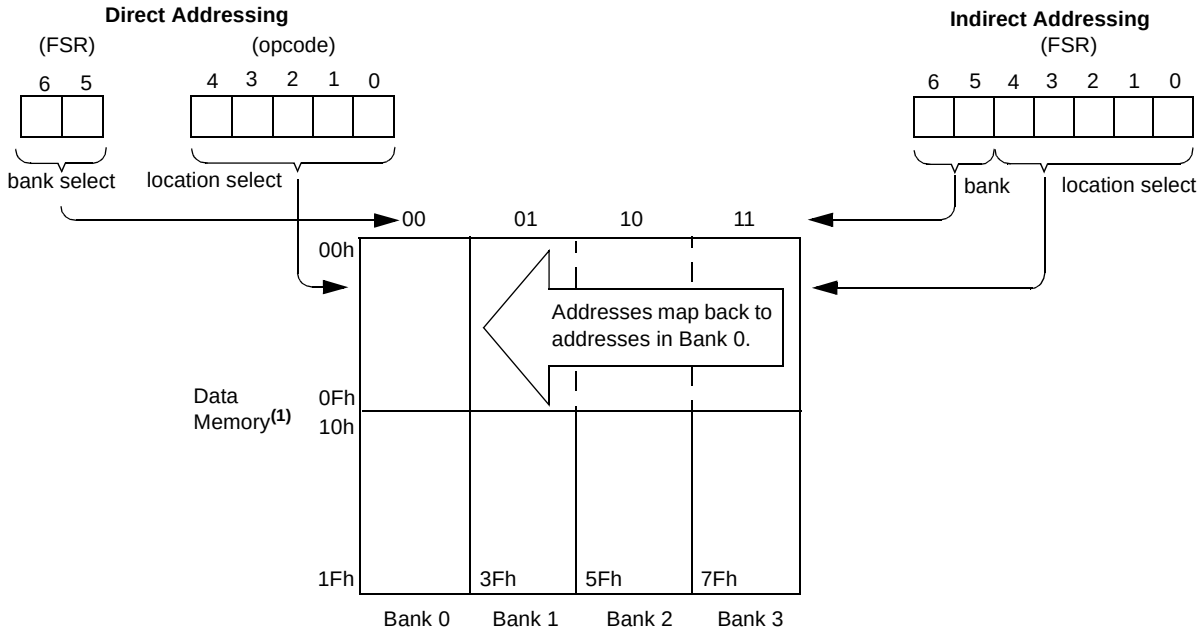
The FSR is either a 5-bit (PIC16C54, PIC16CR54, PIC16C55, PIC16C56, PIC16CR56) or 7-bit (PIC16C57, PIC16CR57, PIC16C58, PIC16CR58) wide register. It is used in conjunction with the INDF Register to indirectly address the data memory area.

The FSR<4:0> bits are used to select data memory addresses 00h to 1Fh.

PIC16C54, PIC16CR54, PIC16C55, PIC16C56, PIC16CR56: These do not use banking. FSR<6:5> bits are unimplemented and read as '1's.

PIC16C57, PIC16CR57, PIC16C58, PIC16CR58: FSR<6:5> are the bank select bits and are used to select the bank to be addressed (`00` = bank 0, `01` = bank 1, `10` = bank 2, `11` = bank 3).

FIGURE 6-10: DIRECT/INDIRECT ADDRESSING



Note 1: For register map detail see Section 6.2.

8.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (TOSC) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

8.1.1 EXTERNAL CLOCK SYNCHRONIZATION

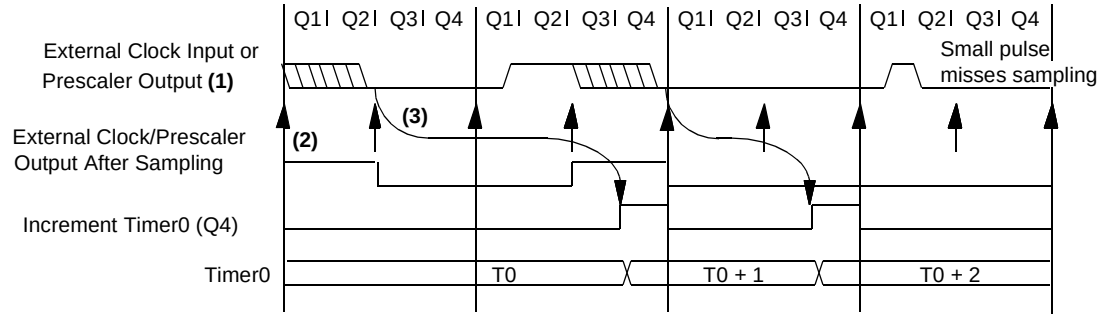
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 8-5). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

8.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 8-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 8-5: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: External clock if no prescaler selected, prescaler output otherwise.
2: The arrows indicate the points in time where sampling occurs.
3: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc (duration of Q = Tosc). Therefore, the error in measuring the interval between two edges on Timer0 input = ± 4Tosc max.

GOTO **Unconditional Branch**

Syntax: [*label*] GOTO k

Operands: $0 \le k \le 511$

Operation: $k \rightarrow PC<8:0>$;
STATUS<6:5> $\rightarrow$ PC<10:9>

Status Affected: None

Encoding:

101k	kkkk	kkkk

Description: GOTO is an unconditional branch. The 9-bit immediate value is loaded into PC bits <8:0>. The upper bits of PC are loaded from STATUS<6:5>. GOTO is a two-cycle instruction.

Words: 1

Cycles: 2

Example:
```
GOTO THERE
```
After Instruction
PC = address (THERE)

INCF **Increment f**

Syntax: [*label*] INCF f,d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (f) + 1 $\rightarrow$ (dest)

Status Affected: Z

Encoding:

0010	10df	ffff

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.

Words: 1

Cycles: 1

Example:
```
INCF   CNT,   1
```
Before Instruction
CNT = 0xFF
Z = 0
After Instruction
CNT = 0x00
Z = 1

INCFSZ **Increment f, Skip if 0**

Syntax: [*label*] INCFSZ f,d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (f) + 1 $\rightarrow$ (dest), skip if result = 0

Status Affected: None

Encoding:

0011	11df	ffff

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
If the result is 0, then the next instruction, which is already fetched, is discarded and a NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example:
```
HERE     INCFSZ    CNT, 1
         GOTO      LOOP
CONTINUE •
         •
         •
```
Before Instruction
PC = address (HERE)
After Instruction
CNT = CNT + 1;
if CNT = 0,
PC = address (CONTINUE);
if CNT ≠ 0,
PC = address (HERE +1)

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: $0 \le f \le 31$

Operation: (W) → (f)

Status Affected: None

Encoding:

0000	001f	ffff

Description: Move data from the W register to register 'f'.

Words: 1

Cycles: 1

Example:
```
MOVWF   TEMP_REG
```
Before Instruction
TEMP_REG = 0xFF
W = 0x4F
After Instruction
TEMP_REG = 0x4F
W = 0x4F

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Encoding:

0000	0000	0000

Description: No operation.

Words: 1

Cycles: 1

Example:
```
NOP
```

OPTION **Load OPTION Register**

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION

Status Affected: None

Encoding:

0000	0000	0010

Description: The content of the W register is loaded into the OPTION register.

Words: 1

Cycles: 1

Example:
```
OPTION
```
Before Instruction
W = 0x07
After Instruction
OPTION = 0x07

RETLW **Return with Literal in W**

Syntax: [*label*] RETLW k

Operands: $0 \le k \le 255$

Operation: k → (W);
TOS → PC

Status Affected: None

Encoding:

1000	kkkk	kkkk

Description: The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.

Words: 1

Cycles: 2

Example:
```
        CALL TABLE ;W contains
                   ;table offset
                   ;value.
        •          ;W now has table
        •          ;value.
TABLE   •
        ADDWF PC   ;W = offset
        RETLW k1   ;Begin table
        RETLW k2   ;
        •
        •
        •
        RETLW kn   ; End of table
```
Before Instruction
W = 0x07
After Instruction
W = value of k8

11.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - ICEPIC™ In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM 2 Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 17 Demonstration Board
  - KEELOQ® Demonstration Board

11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows®-based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or ‘C’)
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
  - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

11.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PIC MCUs.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

11.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI ‘C’ compilers for Microchip’s PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

TABLE 12-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54/55/56/57

AC Characteristics		Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –40°C ≤ TA ≤ +125°C for extended					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
1	TOSC	External CLKIN Period(1)	250	—	—	ns	XT OSC mode
			100	—	—	ns	10 MHz mode
			50	—	—	ns	HS OSC mode (Comm/Ind)
			62.5	—	—	ns	HS OSC mode (Ext)
			25	—	—	µs	LP OSC mode
		Oscillator Period(1)	250	—	—	ns	RC OSC mode
			250	—	10,000	ns	XT OSC mode
			100	—	250	ns	10 MHz mode
			50	—	250	ns	HS OSC mode (Comm/Ind)
			62.5	—	250	ns	HS OSC mode (Ext)
			25	—	—	µs	LP OSC mode
2	Tcy	Instruction Cycle Time(2)	—	4/FOSC	—	—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	85*	—	—	ns	XT oscillator
			20*	—	—	ns	HS oscillator
			2.0*	—	—	µs	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	—	25*	ns	XT oscillator
			—	—	25*	ns	HS oscillator
			—	—	50*	ns	LP oscillator

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.
When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

13.4 DC Characteristics: PIC16CR54A-04E, 10E, 20E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O ports	Vss	—	0.15 VDD	V	Pin at hi-impedance
		MCLR (Schmitt Trigger)	Vss	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	Vss	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	Vss	—	0.15 VDD	V	RC mode only(3)
		OSC1	Vss	—	0.3 VDD	V	XT, HS and LP modes
D040	VIH	**Input High Voltage**					
		I/O ports	0.45 VDD	—	VDD	V	For all VDD(4)
		I/O ports	2.0	—	VDD	V	4.0V < VDD ≤ 5.5V(4)
		I/O ports	0.36 VDD	—	VDD	V	VDD > 5.5V
		MCLR (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	RC mode only(3)
		OSC1	0.7 VDD	—	VDD	V	XT, HS and LP modes
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current(1,2)**					**For VDD ≤ 5.5V:**
		I/O ports	–1.0	0.5	+1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		MCLR	–5.0	—	—	µA	VPIN = VSS + 0.25V
		MCLR	—	0.5	+5.0	µA	VPIN = VDD
		T0CKI	–3.0	0.5	+3.0	µA	VSS ≤ VPIN ≤ VDD
		OSC1	–3.0	0.5	+3.0	µA	VSS ≤ VPIN ≤ VDD, XT, HS and LP modes
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, RC mode only
D090	VOH	**Output High Voltage(2)**					
		I/O ports	VDD – 0.7	—	—	V	IOH = –5.4 mA, VDD = 4.5V
		OSC2/CLKOUT	VDD – 0.7	—	—	V	IOH = –1.0 mA, VDD = 4.5V, RC mode only

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

FIGURE 14-13: MAXIMUM IDD VS. FREQUENCY (EXTERNAL CLOCK, –40°C TO +85°C)

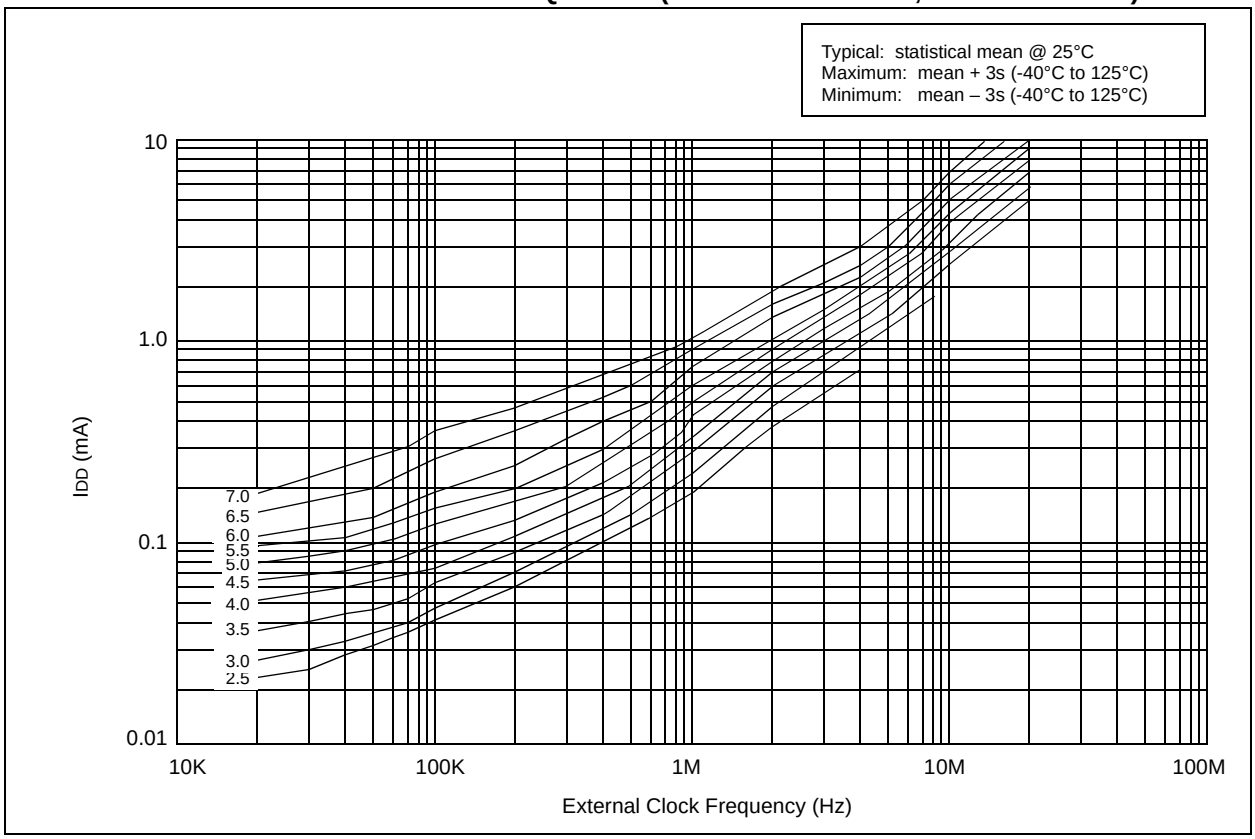
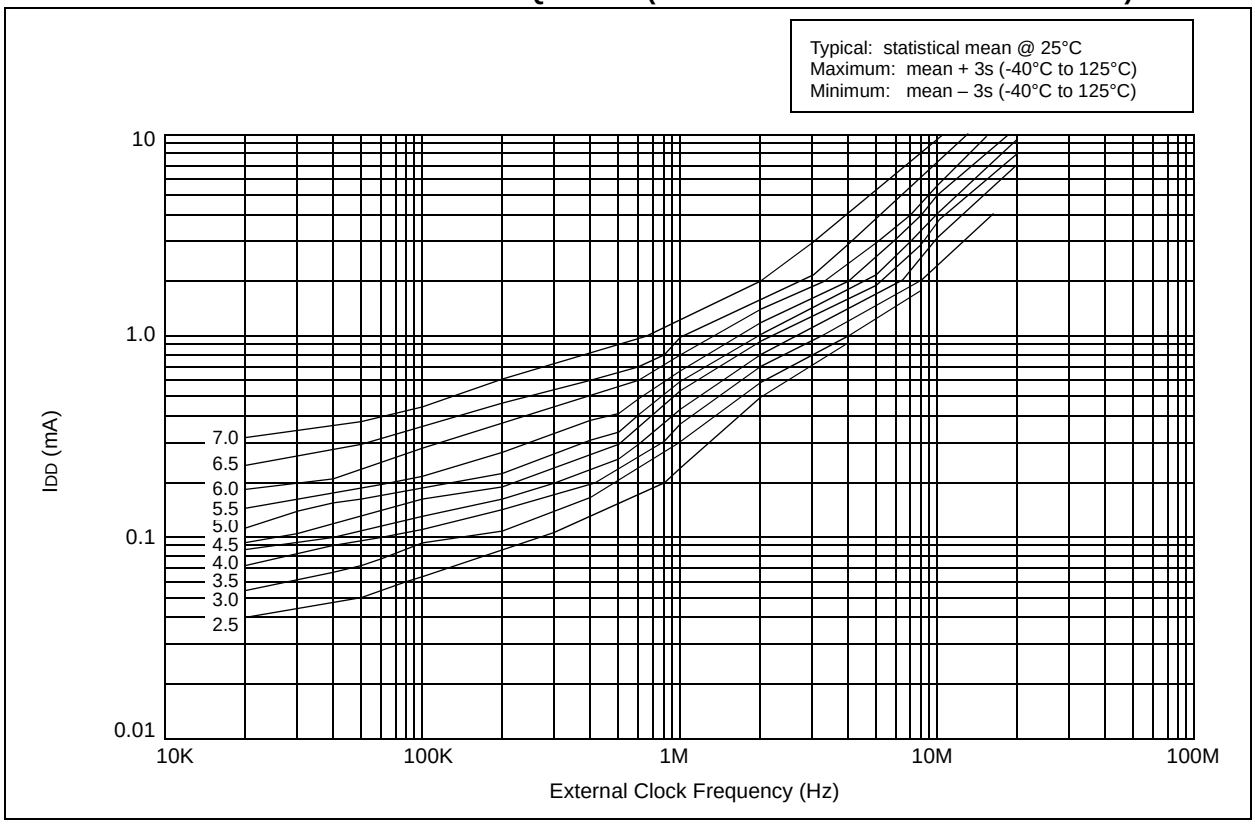


FIGURE 14-14: MAXIMUM IDD vs. FREQUENCY (EXTERNAL CLOCK –55°C TO +125°C)



15.0 ELECTRICAL CHARACTERISTICS - PIC16C54A

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... –55°C to +125°C
Storage temperature ..... –65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... 0 to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} ..... 0 to +14V
Voltage on all other pins with respect to V_{SS} ..... –0.6V to (V_{DD} + 0.6V)
Total power dissipation(1) ..... 800 mW
Max. current out of V_{SS} pin ..... 150 mA
Max. current into V_{DD} pin ..... 100 mA
Max. current into an input pin (T0CKI only) ..... ±500 µA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Max. output current sunk by any I/O pin ..... 25 mA
Max. output current sourced by any I/O pin ..... 20 mA
Max. output current sourced by a single I/O port (PORTA or B) ..... 50 mA
Max. output current sunk by a single I/O port (PORTA or B) ..... 50 mA

Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

† NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16LC54A-04E (Extended)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
PIC16C54A-04E, 10E, 20E (Extended)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC16LC54A	3.0 2.5	— —	6.25 6.25	V V	XT and RC modes LP mode
D001A		PIC16C54A	3.5 4.5	— —	5.5 5.5	V V	RC and XT modes HS mode
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
	IDD	**Supply Current(2)**					
D010		PIC16LC54A	—	0.5	25	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes
			—	11	27	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	11	35	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
			—	11	37	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Extended
D010A		PIC16C54A	—	1.8	3.3	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC(3) and XT modes
			—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V, HS mode
			—	9.0	20	mA	FOSC = 20 MHz, VDD = 5.5V, HS mode

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

FIGURE 16-7: VTH (INPUT THRESHOLD VOLTAGE) OF I/O PINS - VDD

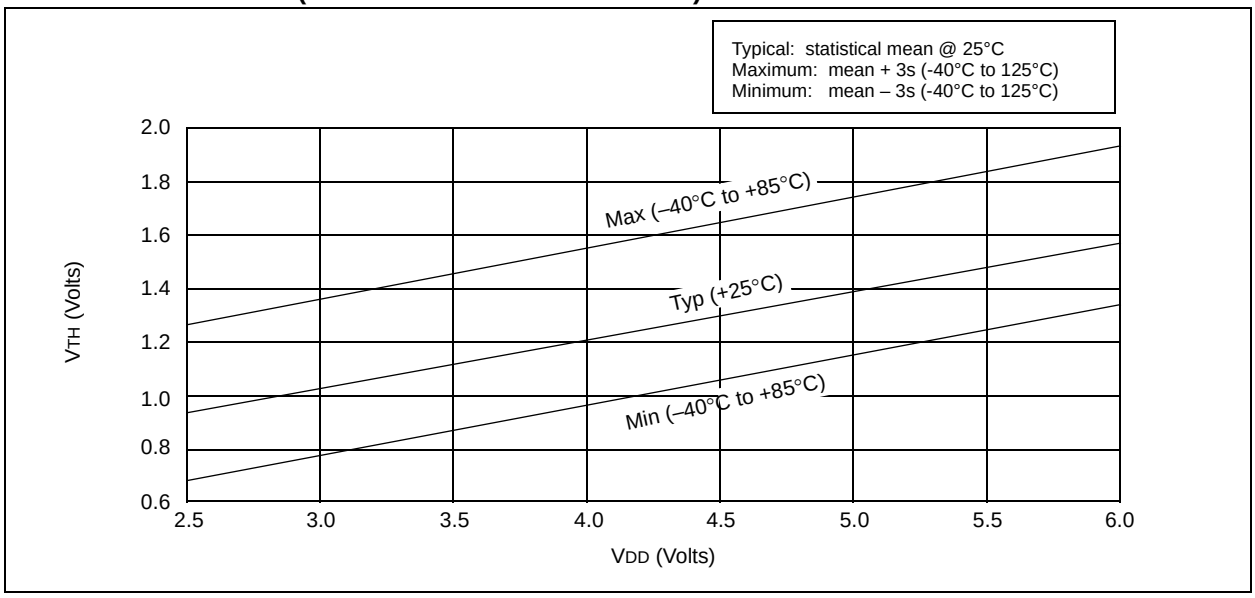
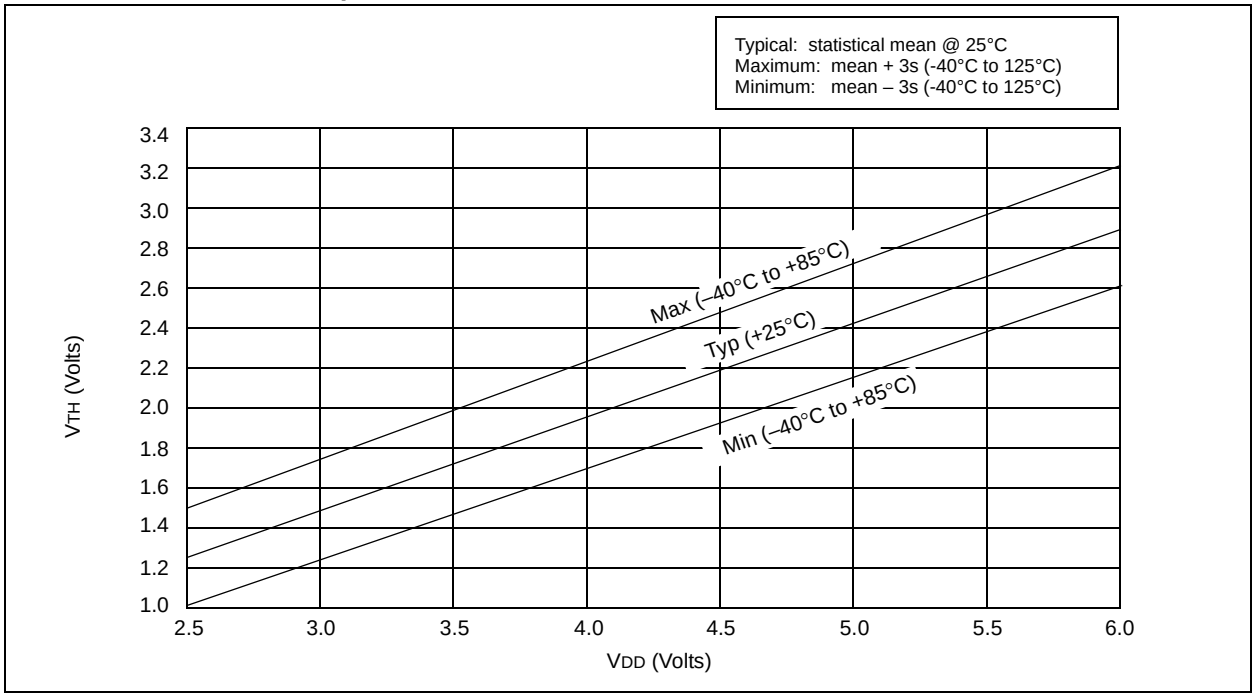
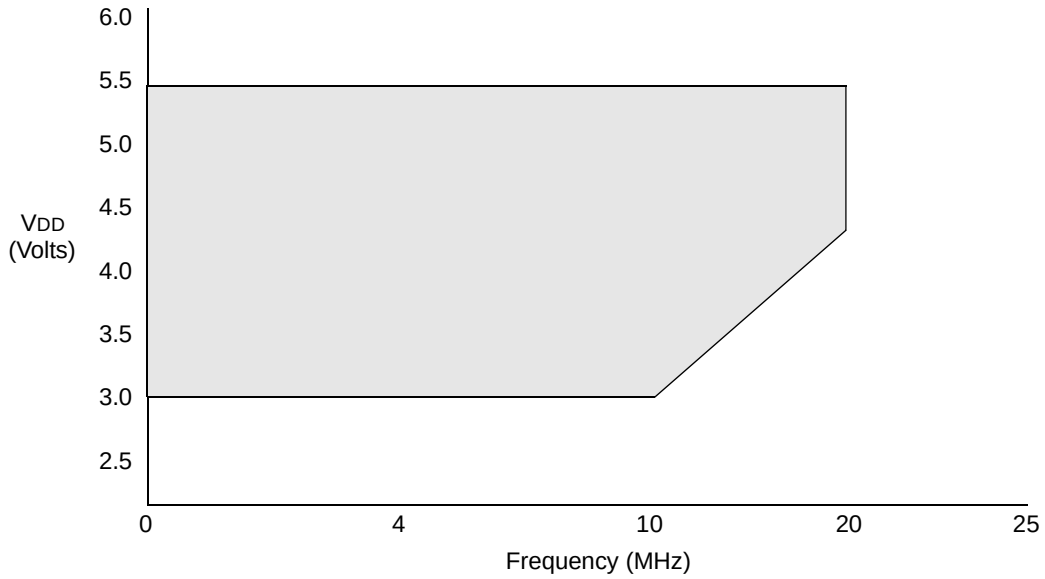


FIGURE 16-8: VTH (INPUT THRESHOLD VOLTAGE) OF OSC1 INPUT (IN XT, HS, AND LP MODES) vs. VDD



NOTES:

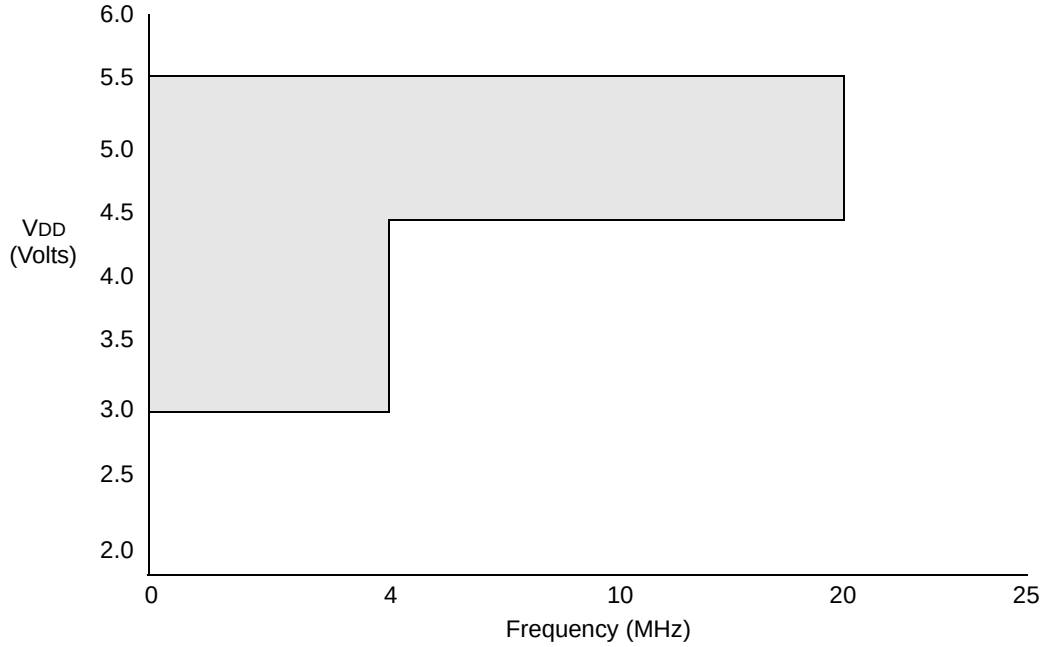
FIGURE 17-1: PIC16C54C/55A/56A/57C/58B-04, 20 VOLTAGE-FREQUENCY GRAPH, 0°C ≤ T_A ≤ +70°C (COMMERCIAL TEMPS)



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

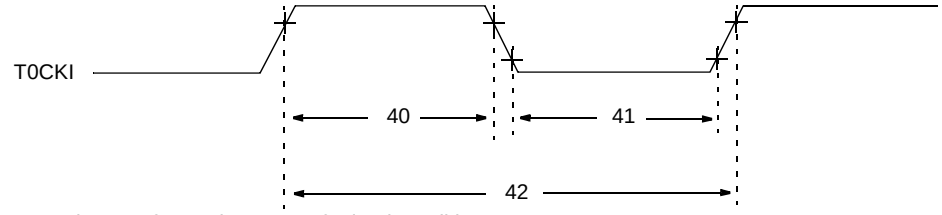
FIGURE 17-2: PIC16C54C/55A/56A/57C/58B-04, 20 VOLTAGE-FREQUENCY GRAPH, -40°C ≤ T_A < 0°C, +70°C < T_A ≤ +125°C (OUTSIDE OF COMMERCIAL TEMPS)



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 17-9: TIMER0 CLOCK TIMINGS - PIC16C5X, PIC16CR5X



Note: Please refer to Figure 17-5 for load conditions.

TABLE 17-4: TIMER0 CLOCK REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Characteristics			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
40	Tt0H	T0CKI High Pulse Width - No Prescaler	0.5 TCY + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width - No Prescaler	0.5 TCY + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period	20 or $\frac{T_{CY} + 40}{N}$*	—	—	ns	Whichever is greater. N = Prescale Value (1, 2, 4,..., 256)

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

20.0 DEVICE CHARACTERIZATION - PIC16LC54C 40MHz

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 20-1: TYPICAL IPD vs. VDD, WATCHDOG DISABLED (25°C)

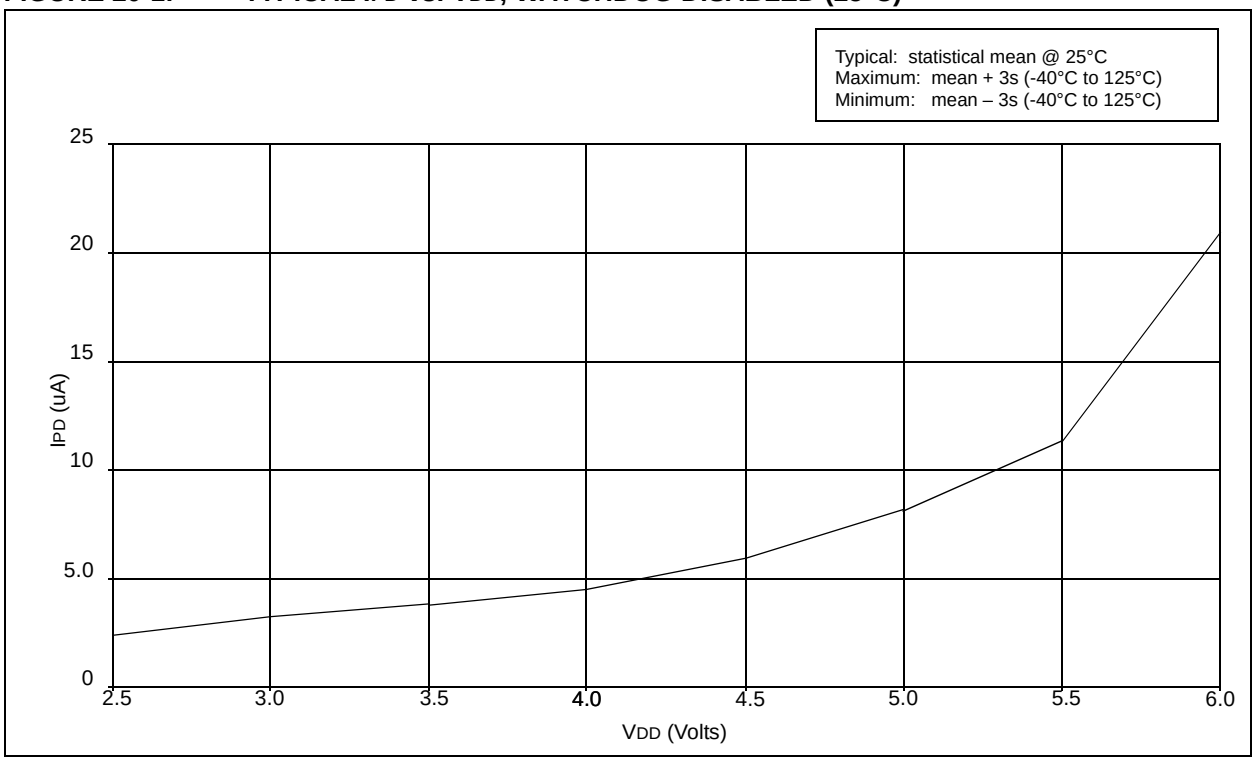


FIGURE 20-4: VTH (INPUT THRESHOLD TRIP POINT VOLTAGE) OF I/O PINS vs. VDD

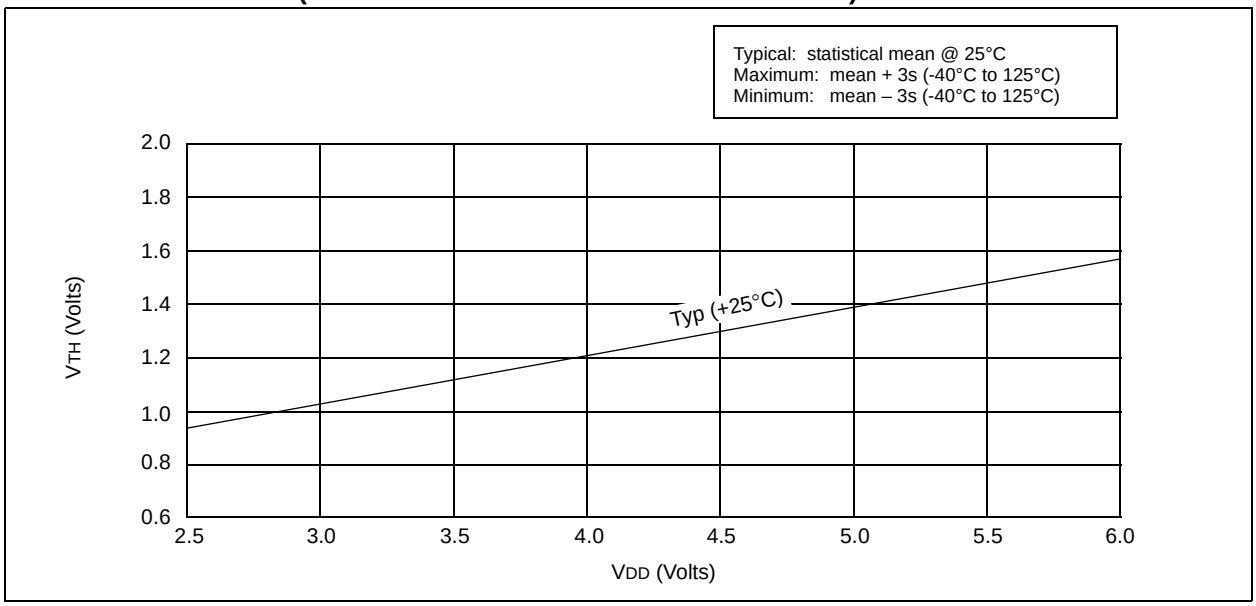
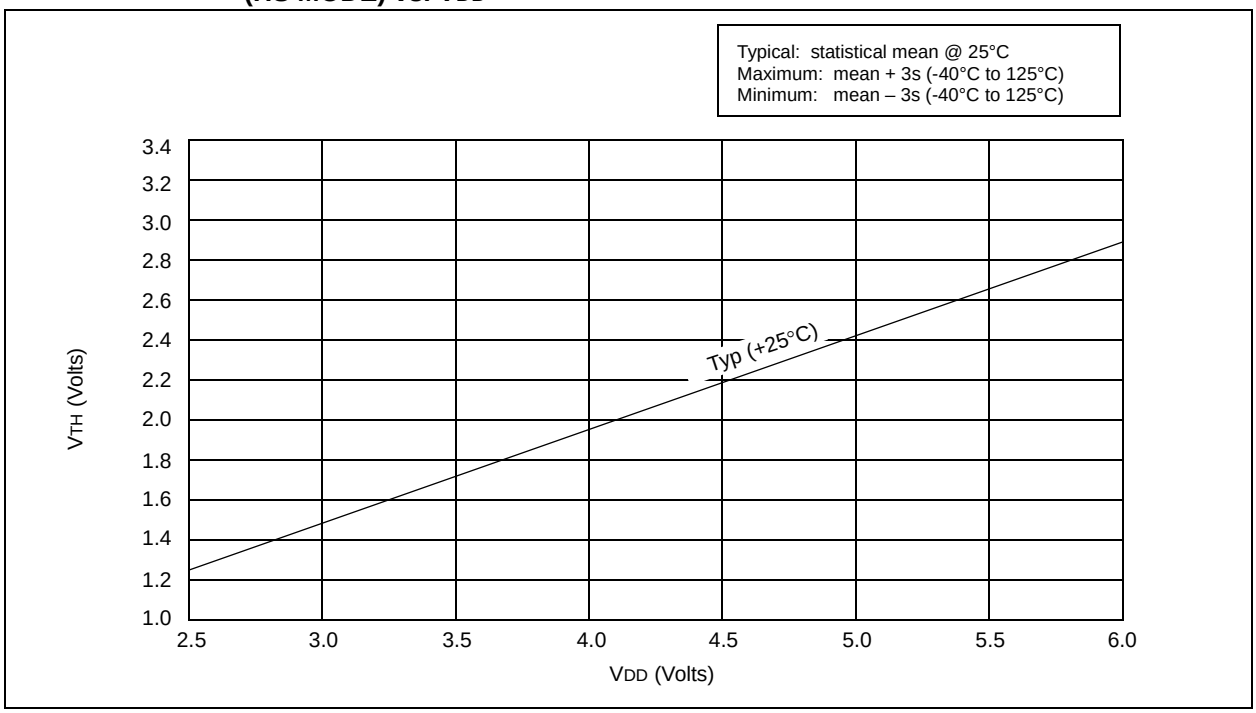
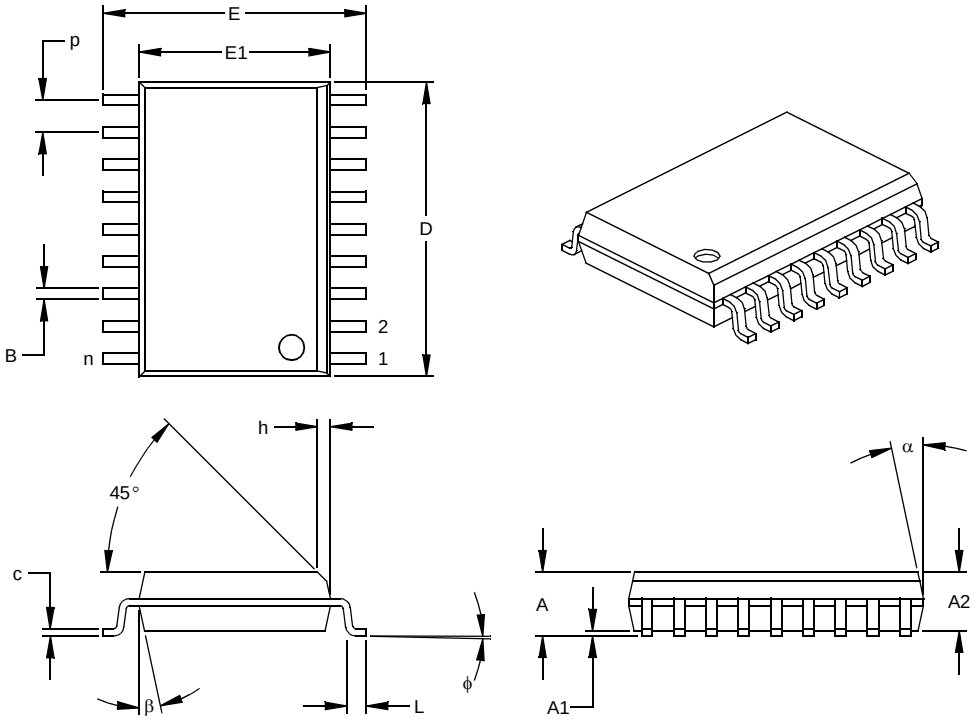


FIGURE 20-5: VTH (INPUT THRESHOLD TRIP POINT VOLTAGE) OF OSC1 INPUT (HS MODE) vs. VDD



18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	ϕ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-051

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